AGENDA (Status: July 4, 2023)

Overview

Day	Date	Subject
DAY 0	Tue, July 4	EPoSS Day – EPoSS Members only
DAY 1	Wed, July 5	Annual Forum • Opening, Sessions
DAY 2	Thu, July 6	Annual Forum • Funding, Start-up Award, • Posters, Company Corner • Site Visits
DAY 3	Fri, July 7	Annual Forum • Sessions, Closing
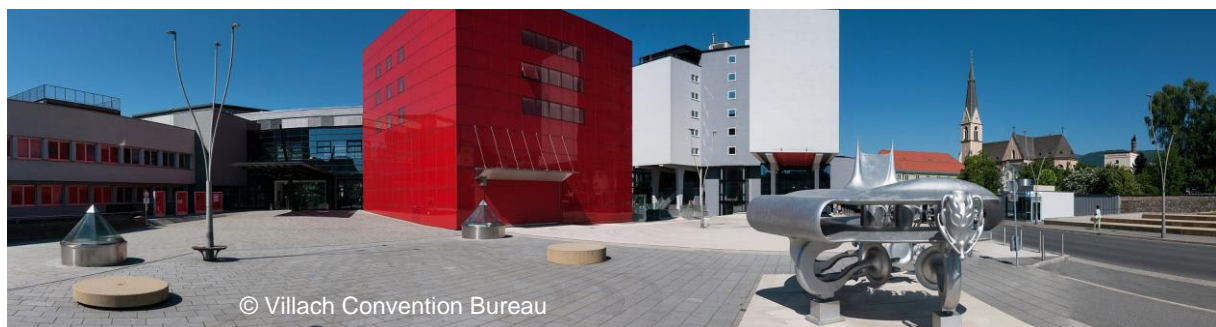
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EPoSS Annual Forum 2023

FROM IDEAS TO
NEXT GENERATION
SMART SYSTEMS

4–7 JULY 2023, VILLACH, AUSTRIA

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DAY 0 – Tuesday, July 4, 2023 | EPoSS Day – EPoSS Members only

Time	Subject	
12:00 – 13:00	Registration and Sandwich Lunch	
13:00 – 15:00	**EPoSS Executive Committee Meeting** *Chairman: Albrecht Donat, Siemens AG*	
15:00 – 15:15	Coffee Break	
15:15 – 18:05	**Parallel EPoSS Working Group Meetings**	
	Room: Drau Galerie	*Room: Gottfried-v.-Einem-Saal*
15:15 – 15:50	**WG Energy** *Chairman: Thomas Hammer, Siemens AG*	**WG Healthy Living** *Chairman: Rainer Günzler, Hahn-Schickard; Michael Scholles, Fraunhofer*
15:50 – 16:25	**WG Food, Agriculture, Natural Resources** *Chairman: Cian O´Murchu, Tyndall National Institute*	**WG Factory Automation** *Chairmen: Antonio Lionetto, STMicroelectronics; Harald Pötter, Fraunhofer IZM*
16:25 – 16:55	Coffee Break	
	Room: Drau Galerie	*Room: Gottfried-v.-Einem-Saal*
16:55 – 17:30	**WG Green ECS** *Chairman: Matthias Straub, microTEC Südwest*	**TF EDIH** *Chairman: Rainer Günzler, Hahn-Schickard*
17:30 – 18:05	**WG AI at the Edge** *Chairman: Kay Bierzinski, Infineon*	**WG Transportation** *Chairmen: Wolfgang Dettmann, Infineon; Gereon Meyer, VDI/VDE-IT; Riccardo Groppo, Ideas & Motion*
18:15 – 19:00	**Key Tech Meeting** *Chairman: Sven Rzepka, Fraunhofer ENAS*	
19:15	**EPoSS Executive Committee Dinner** *Restaurant Burgarena Finkenstein* *20min Bus transfer: 19:15 from Congress Center (CVV) / Main Entrance*	

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DAY 1 – Wednesday, July 5, 2023

Time	Subject		
11:30	**Start of Annual Forum 2023**	**09:00 – 11:00**	**EPoSS General Assembly** **EPoSS Members only**
11:00 – 11:30	Registration and Welcome Coffee		
11:30 – 13:00	**Chips Act: How will we realise the Next Generation of Smart Systems made in Europe? Opening Session** *Moderator: Elisabeth Steimetz, EPoSS Director*		
11:30 – 11:33	Introduction of Agenda	Moderator	
11:33 – 11:45	Welcome by the Carinthian government	Gaby Schaunig, Deputy-Governor of Carinthia	
11:45 – 12:00	Welcome by the EPoSS Chairman	Stefan Finkbeiner, CEO Bosch Sensortech	
12:00 – 12:20	The Chips Act and the Chips JU	Colette Maloney, DG CNECT, European Commission (online)	
12:20 – 12:30	Note from the Austrian Public Authorities	Michael Wiesmüller, Head of Department Austrian Ministry for Climate Action, Environment, Energy, Mobility, Innovation and Technology (online)	
12:30 – 12:45	Notes from a European industry leader	Sabine Herlitschka, CEO Infineon Technologies Austria AG	
12:45 – 13:00	Panel Discussion	Speakers of the Opening Session	
13:00 – 14:00	Lunch and Networking		
14:00 – 15:30	**Session 1 | Towards the Next Generation Smart Systems: Quantum Technologies** *Chairwoman: Christina Hirschl, Silicon Austria Labs*		
14:00 – 14:20	Quantum Technology – from fundamental science to full-scale devices	Michael Trupke, Universität Wien	
14:20 – 14:40	#CreateTheUnthinkable – the Power of Quantum Sensing	Katrin Kobe, Bosch Quantum Sensing	
14:40 – 15:00	Quantum Computing with Trapped Ions	Yves Colombe, Infineon	

DAY 1 – Wednesday, July 5, 2023

Time	Subject	
15:00 – 15:20	Strategic industry roadmapping for quantum technologies	Anna Kaminska, Creotech Instruments
15:20 – 15:30	Q&As	
15:30 – 15:45	Coffee break	
15:45 – 17:00	**Session 2 | Latest Integration Technologies for Tomorrow's Smart Systems** *Chairman: Wolfgang Dettmann, Infineon Technologies*	
15:45 – 16:00	Sub-micron die attach for high-volume manufacturing	Birgit Brandstätter, Besi Austria GmbH
16:00 – 16:15	Wafer bonding technologies for simultaneous mechanical and electrical contacting	Dirk Wünsch, Fraunhofer Institute for Electronic Nano Systems ENAS
16:15 – 16:30	Micro-Transfer Printing: A novel Approach for Chiplet Integration	Tino Jäger, X-FAB
16:30 – 16:45	Silicon nitride platform for Photonic Integrated Circuits: An Open Access Foundry	Jad Sabek, Microelectronics Institute of Barcelona (IMB-CNM)
16:45 – 17:00	High-performance MEMS and large-aperture Fabry-Pérot interferometers and nano-thermoelectric bolometers for spectral imaging and sensing	Aapo Varpula, VTT Technical Research Centre of Finland
17:00 – 17:15	Break	
17:15 – 18:30	**Evening Session: How to address the skills shortage in Europe?** *Moderator: Robert Gfrerer, Silicon Alps Cluster* Christina Hirschl, Silicon Austria Labs | Stefanie Rud, Ortner Cleanroom Engineering | Frank Bösenberg, Silicon Saxony / Silicon Europe Alliance | Luis Fonseca, Institute of Microelectronics of Barcelona (IMB-CNM)	
19:30	**EPoSS Dinner Event** *Restaurant CCV including River DRAU Water Games, Villach*	

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DAY 2 – Thursday, July 6, 2023

Time	Subject	
08:00 – 09:00	Registration and Welcome Coffee	
09:00 – 09:15	**EPoSS Spotlight** *Chairman: Sven Rzepka, Fraunhofer ENAS (tbc)*	
	Introduction to the EPoSS White Paper on Integrated photonics	Michael Scholles, Fraunhofer Institute for Photonic Microsystems IPMS
09:15 – 10:15	**Funding Opportunities: KDT, Xecs and regional calls** *Chairwoman: Elisabeth Steimetz, EPoSS Director*	
09:15 – 09:30	KDT JU and Chips JU Calls 2023/2024	Yves Gigase, KDT JU
09:30 – 09:45	Xecs Calls and Update	Nadja Rohrbach, Aeneas
09:45 – 10:00	EARASHI open call, a new funding opportunity for Start-up and SME	Isabelle Dor, CEA
10:00 – 10:15	Driving manufacturing SMEs towards green, digital and social sustainability – the Open Call of the greenSME project	Fabrizio Fallarini, MESAP Innovation Cluster
10:15 – 11:00	**Company Corner (Foyer area) and Poster Pitches** *Chairman: Martin Martens, EPoSS Association*	
11:00 – 12:00	**Company Corner and Poster Session (Foyer area incl. coffee)**	
12:00 – 13:00	**EPoSS Start-up Award** *Chairman: Andreas Klug, AVL List GmbH (tbc)*	
13:00 – 14:00	Lunch and Networking	
14:00 – 18:30	**Site Visits | Infineon, Silicon Austria Labs**	
19:00	**EPoSS Dinner Event & Start-up Award Ceremony** *Stiftsschmiede, Lake Ossiach* *20min Bus transfer: 19:00 from Congress Center (CVV) / Main Entrance*	

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DAY 3 – Friday, July 7, 2023

Time	Subject	
08:00 – 08:45	Registration and Welcome Coffee	
08:45 – 09:45	**Session 3 | The Next Generation of Smart Systems for Future Applications** *Chairman: Michael Offenberg, Bosch*	
08:45 – 09:00	MEMS sensors for smart sustainable condition monitoring	Achim Bittner, Hahn-Schickard
09:00 – 09:15	System architecture for MEMS: From idea to product	Matthias Kühnel, Robert Bosch GmbH
09:15 – 09:30	Sensor systems with internal data processing and storage as well as wireless interface running without electrical energy storage and energy harvesting devices	Sven Zimmermann, Fraunhofer Institute for Electronic Nano Systems ENAS
09:30 – 09:45	Trusted Smart Sensors for the Internet of Things	Dirk Mayer, Fraunhofer EAS
09:45 – 10:45	**Session 4 | The Upcoming Meta Topic: Green Smart Systems and Smart Systems for Green** *Chairwoman: Suzanna Lesecq, CEA*	
09:45 – 10:00	Introduction to the EPoSS White Paper on Green ECS	Matthias Straub, microTEC Südwest
10:00 – 10:15	Green Electronic Systems for Digital Innovation: Challenges and Opportunities	Sabine K. Lengger, Silicon Austria Labs GmbH
10:15 – 10:30	Low-power ultrasonic acoustic emission sensor systems for novel field-applications in precision agriculture, biology, forestry, and industrial NDT	Dinko Oletić, University of Zagreb
10:30 – 10:45	OE-A & OE-A Working Group Sustainability	Jérôme Gavillet, CEA
10:45 – 11:00	Coffee Break	

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DAY 3 – Friday, July 7, 2023

Time	Subject	
11:00 – 12:30	**Session 5 | Tomorrow's Mobility enabled by Smart Systems** *Chairman: Martin Martens, VDI/VDE-IT*	
11:00 – 11:15	Digital Chassis: Unleashing the benefits of In-wheel propulsion system	Gorzad Lampic, Elaphe
11:15 – 11:30	Unfolding Sustainable Future with Smart Road Lighting Technology	Adrien Piot, Silicon Austria Labs
11:30 – 11:45	Trustable sensor-driven electronic systems for Automotive, Aviation and Industrial Applications (TRUST-E)	Kai Kriegel, Siemens AG
11:45 – 12:00	Advanced Measurement Concepts and Components for Development and Validation of Fuel Cell Electric Vehicles	Markus Reiter, AVL List GmbH
12:00 – 12:15	Predictive Health Management of Powertrain Components Towards Longer Lifetime	Sajib Chakraborty, Vrije Universiteit Brussel
12:15 – 12:30	Q&A	
12:30 – 13:00	**Annual Forum Closing Session**	
13:00 – 14:00	Lunch and Networking	
14:00	**End of Annual Forum 2023**	

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APPENDIX | Poster Session | Sequence and Themes
DAY 2 – Thursday, July 6, 2023, 10:15 – 12:00

10:15 – 12:00	**Poster Pitches and Poster Sessions** *Chairman: Martin Martens, EPoSS Association*	
1	AR and its components	Marko Pudas, Dispelix Oy
2	NoldusHub – a new software platform for integration, synchronization and analysis of multi-modal sensor data	Andrew Spink, Noldus Information Technology BV
3	A comparative study among pressure-less, pressure-assisted Cu sinter pastes and Cu-based transient liquid phase sintering paste for indirect bonding of Cu pillars	Augusto Rodrigues, Silicon Austria Labs GmbH
4	Feedback-enhanced pick-and-place technologies as foundation for novel manufacturing processes in automotive sensor packages	Benedikt Pressl, Besi Austria GmbH
5	Implementation and Testing of 3d Visual Slam on a mobile robotic platform using TOF-camera with cliff detection capabilities in GPS–denied dark visually–degraded environments	Paras Sikka, Infineon Technologies Austria
6	Development of data-driven digital twin model from a physics-based hi-fidelity model for Power Electronics Systems	Sachin Kumar Bhoi, Vrije Universiteit Brussel
7	Computer vision: a solution for the management of loading and unloading zones	Javier Romo, CIDAUT Foundation

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